

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	541	257/706.ccls. and (heat adj (sink slug element spreader plate radiation)) and (mold\$4 encapsula\$4 packag\$4) and (insulat\$4 dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:33
L2	342	L1 and @ad<="20010702"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:33
L3	1294	257/712-718.ccls. and (heat adj (sink slug element spreader plate radiation)) and (mold\$4 encapsula\$4 packag\$4) and (insulat\$4 dielectric)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:33
L4	951	L3 and @ad<="20010702"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 12:33
L5	774	L4 not L2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 15:58
L8	1	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) with (second adj length)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:05
L9	338	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) with length	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:56
L10	117	9 and (chip die IC (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:09
L11	2	("6611011").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/09 16:10

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L12	2	("6611001").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/03/09 16:10
L14	3	(molding adj line) with (lead support paddle) with (expos\$3 protrud\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:57
L15	2412	((encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:59
L16	127	((encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:13
L17	0	16 not 15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:58
L18	0	((mold\$3 adj line) with (lead support paddle) with (expos\$3 protrud\$3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 16:59
L19	10	(mold\$3 adj line) with (lead support paddle) with (expos\$3 protrud\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:01
L21	1237	((encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) with (length surface)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:08
L22	791	21 and (chip die IC (integrated adj circuit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:15

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L23	709	22 and second	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:10
L24	50	amano-kenji.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:30
L30	7	("5294827"   "5521429"   "5841187"   "5844307"   "5900676"   "5973388"   "5977613").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/09 17:19
L31	181	fujisawa-atsushi.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:33
L32	29	hasebe-hajime.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:33
L34	61	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/666-670.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:39
L35	37	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/672,674,676,678.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:41
L36	34	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/690-693.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:44

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L37	54	( "20040036180"   "3838984"   "4159221"   "4398235"   "4833568"   "4956694"   "4996587"   "5068713"   "5230759"   "5258094"   "5266834"   "5332864"   "5381039"   "5381047"   "5394010"   "5414300"   "5435057"   "5455387"   "5521429"   "5581118"   "5587341"   "5594275"   "5625221"   "5677569"   "5715147"   "5742007"   "5760471"   "5835988"   "5852320"   "5859471"   "5877043"   "5880403"   "5950074"   "5962810"   "5977613"   "5986209"   "6114221"   "6130115"   "6143981"   "6180881"   "6225146"   "6235554"   "6242281"   "6281568"   "6320251"   "6356453"   "6404046"   "6433418"   "6459148"   "6518659"   "6564454"   "6577013"   "6646339"   "6730544").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/03/09 17:42
L38	29	(encapsulation encapsulant encapsulating sealing sealant seal molding mold\$2) with (lead support paddle) with (expos\$3 protrud\$3) same length and 257/787-788.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/03/09 17:44